

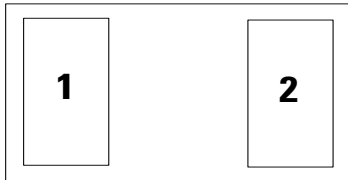
**AQ3118 Series 0.3pF 10 kV Bidirectional Discrete TVS**



**Description**

The AQ3118 includes back-to-back TVS diodes fabricated in a proprietary silicon avalanche technology to provide protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes up to the maximum level specified in IEC 61000-4-2 international standard without performance degradation. The back-to-back configuration provides symmetrical ESD protection for data lines when.

**Pinout**



**Features**

- ESD protection of  $\pm 10\text{kV}$  contact discharge,  $\pm 15\text{kV}$  air discharge, (IEC 61000-4-2)
- EFT protection, IEC 61000-4-4, 40A ( $t_p=5/50\text{ns}$ )
- Lightning, 2A (8/20 $\mu$  as defined in IEC 61000-4-5 2<sup>nd</sup> edition)
- Low capacitance of 0.3pF @  $V_R=0\text{V}$
- Low leakage current of 50nA (max) at 18V
- Space efficient 0402 footprint
- AEC-Q101 qualified
- Halogen free, lead free and RoHS compliant
- Moisture Sensitivity Level(MSL -1)
- PPAP capable

**Functional Block Diagram**



**Applications**

- Tablets
- Ultrabook
- eReader
- Smart Phones
- Digital Cameras
- MP3/ PMP
- Set Top Boxes
- Portable Medical
- NFC and FeliCa
- Automotive applications

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	2.0	A
$T_{OP}$	Operating Temperature	-40 to 150	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

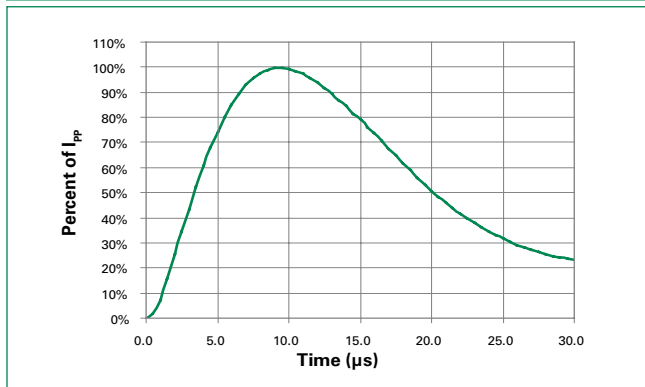
**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

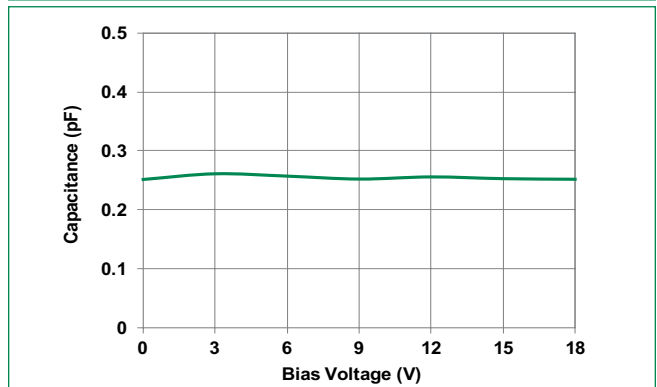
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Breakdown Voltage	$V_{BR}$	$I_R=1mA$	20		30	V
Reverse Standoff Voltage	$V_{RWM}$				18	V
Reverse Leakage Current	$I_{LEAK}$	$V_R=18V$ with 1 pin at GND		1	50	nA
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		31	35	V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		34	38	V
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact)	$\pm 10$			kV
		IEC 61000-4-2 (Air)	$\pm 15$			kV
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP, $t_p=100ns, I/O$ to GND		0.75		$\Omega$

**Note:** 1. Parameter is guaranteed by design and/or component characterization.  
 2. Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window  $t_1=70ns$  to  $t_2=90ns$

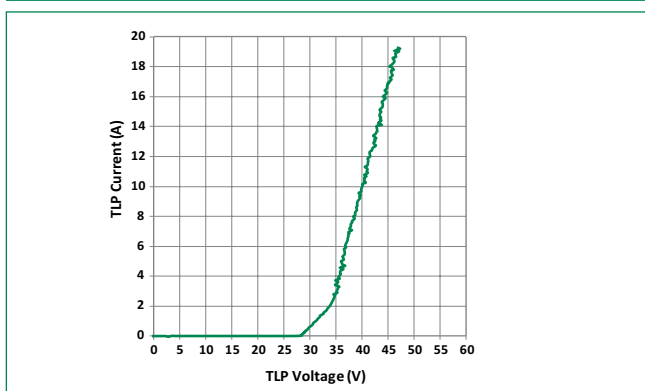
### 8/20 $\mu s$ Pulse Waveform



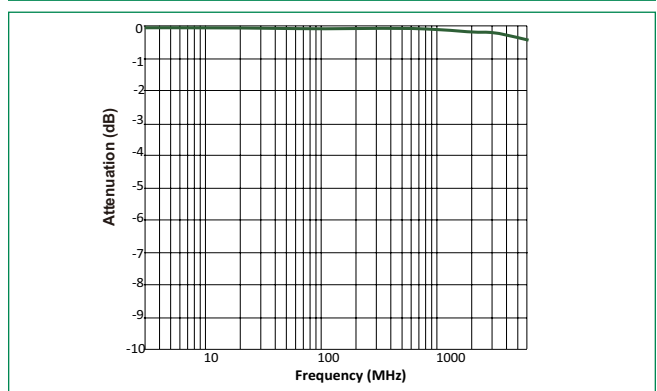
### Capacitance vs. Reverse Bias



### Transmission Line Pulsing (TLP) Plot

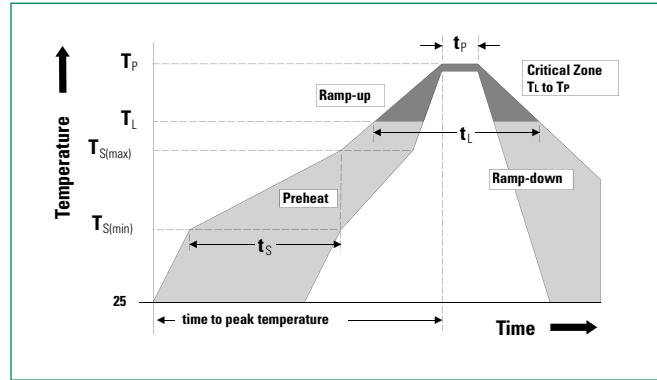


### Insertion Loss (S21)

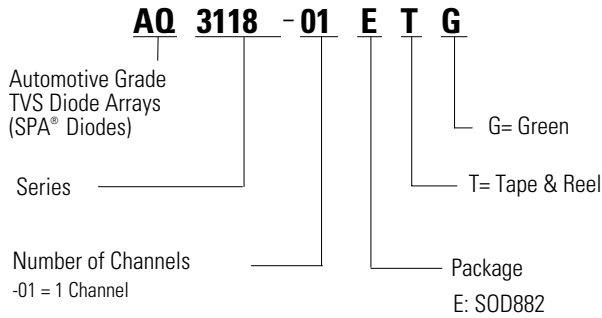


### Soldering Parameters

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_p$ )	60 – 180 secs
<b>Average ramp up rate (Liquidus) Temp (<math>T_L</math>) to peak</b>		3°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		260°C



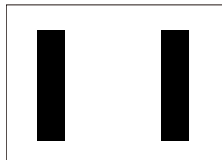
### Part Numbering System



### Product Characteristics

<b>Lead Plating</b>	Pre-Plated Frame
<b>Lead Material</b>	Copper Alloy
<b>Substrate material</b>	Silicon
<b>Body Material</b>	Molded Compound
<b>Flammability</b>	UL Recognized compound meeting flammability rating V-0

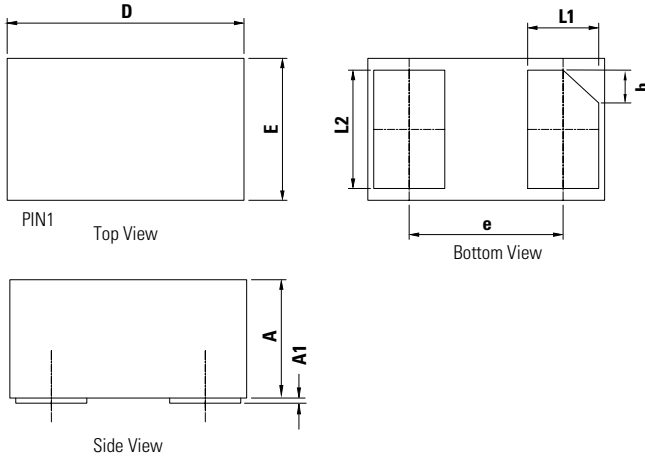
### Part Marking System



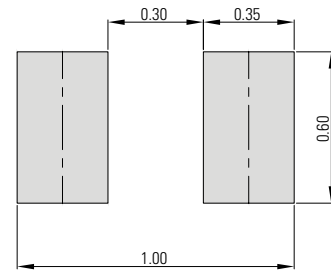
### Ordering Information

Part Number	Package	Min. Order Qty.
AQ3118-01ETG	SOD882	10000

**Package Dimensions — SOD882**

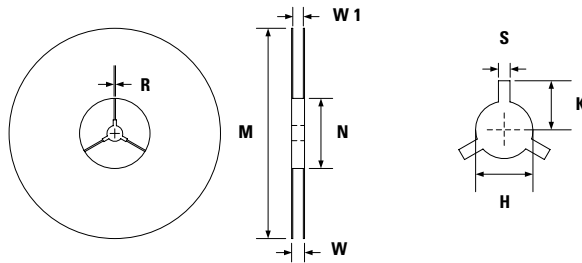
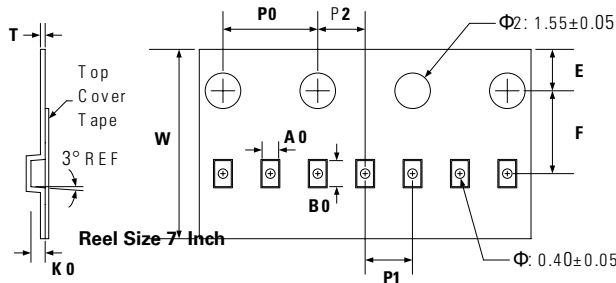


Symbol	Dimensions		
	Min	Nor.	Max
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
L1	0.20	0.25	0.30
L2	0.45	0.50	0.55
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	0.65BSC		
h	0.07	0.12	0.17



Recommended Soldering Pad Layout (mm)

**Embossed Carrier Tape & Reel Specification — SOD882**



Symbol	Tape Dimensions	
	Millimetres	
	Min	Max
A0	0.65	0.75
B0	1.10	1.20
K0	0.50	0.60
E	1.65	1.85
F	3.45	3.55
P0	3.90	4.10
P1	1.90	2.10
P2	1.95	2.05
T	1.95	2.05
W	7.90	8.10

Symbol	Reel Dimensions (Size $\Phi 178$ )	
	Millimetres	
	Min	Max
M	177.0	179.0
N	59.0	61.0
W	11.0	12.0
W1	8.5	9.5
H	12.5	13.5
S	1.9	2.1
K	10.8	11.2
R	0.95	1.05

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